

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00168

REV: E1

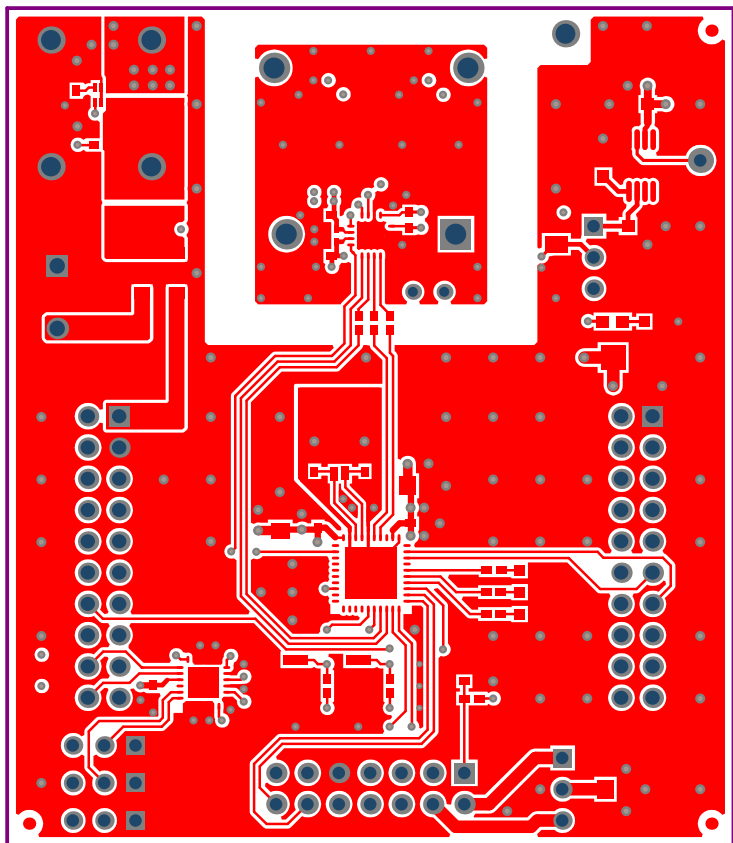
SVN REV: Not In VersionControl

LAYER NAME = Top Solder

PLOT NAME = Top Solder Mask

GENERATED : 10/1/2014 11:55:07 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00168

REV: E1

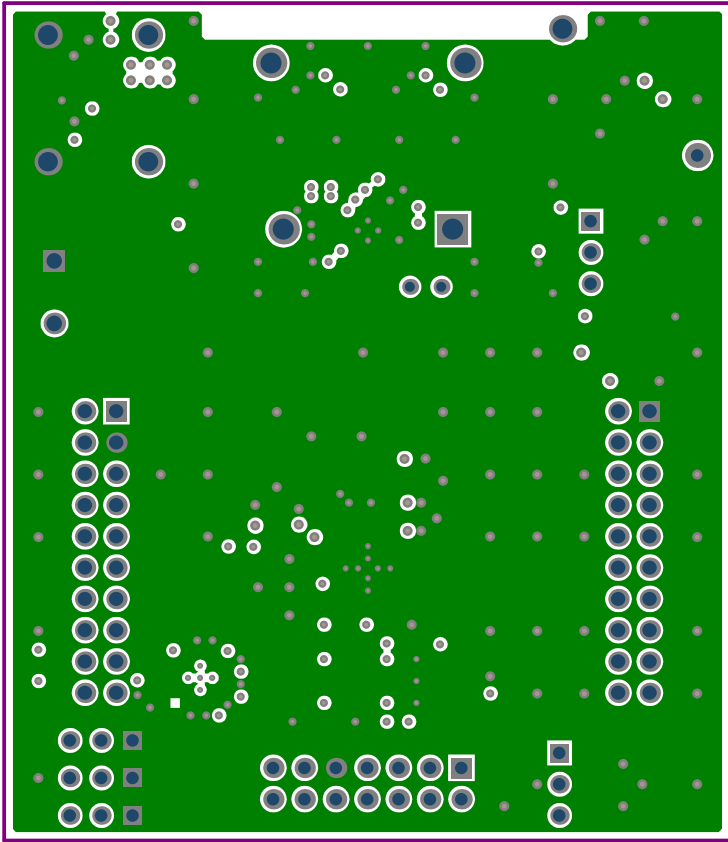
SVN REV: Not In VersionControl

LAYER NAME = Top Layer

PLOT NAME = Top Layer

GENERATED : 10/1/2014 11:55:07 AM

TEXAS INSTRUMENTS



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REV: E1

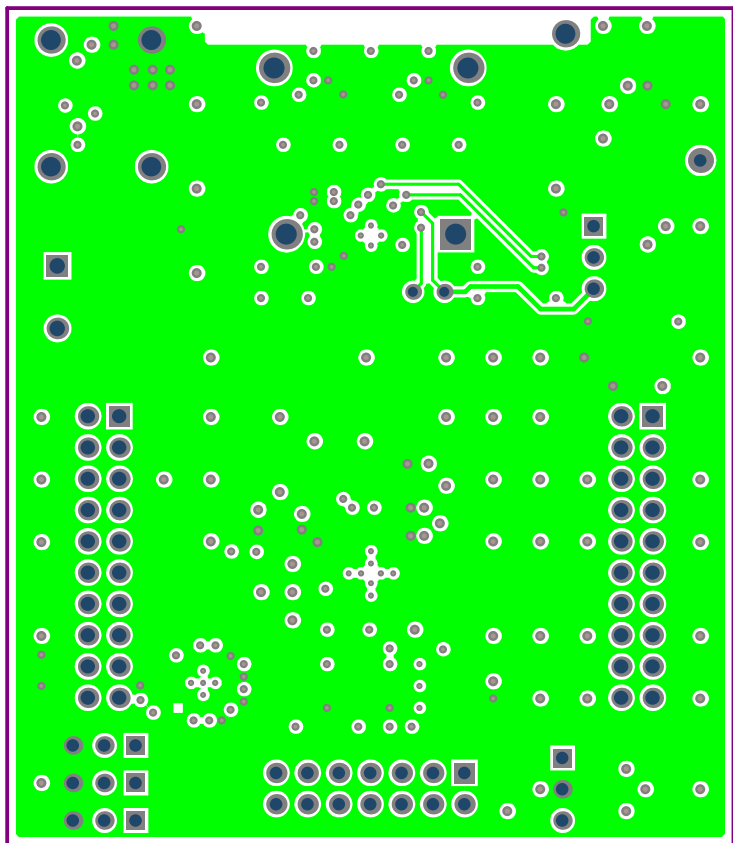
SVN REV: Not In VersionControl

LAYER NAME = Layer2\_GND Plane

PLOT NAME = MidLayer1

GENERATED : 10/1/2014 11:55:07 AM

TEXAS INSTRUMENTS



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REV: E1

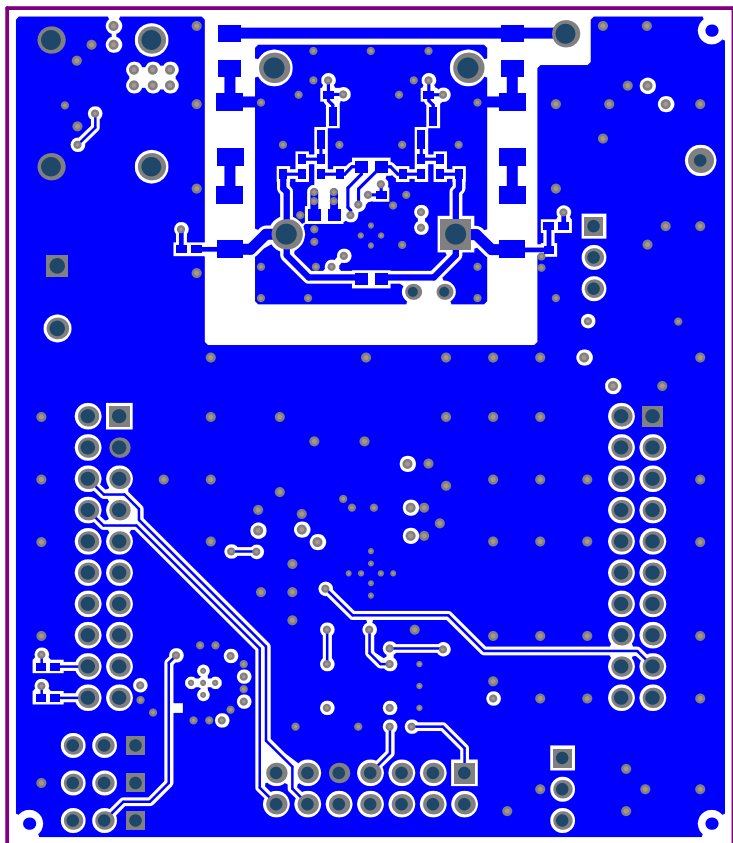
SVN REV: Not In VersionControl

LAYER NAME = Layer3\_VCC Plane

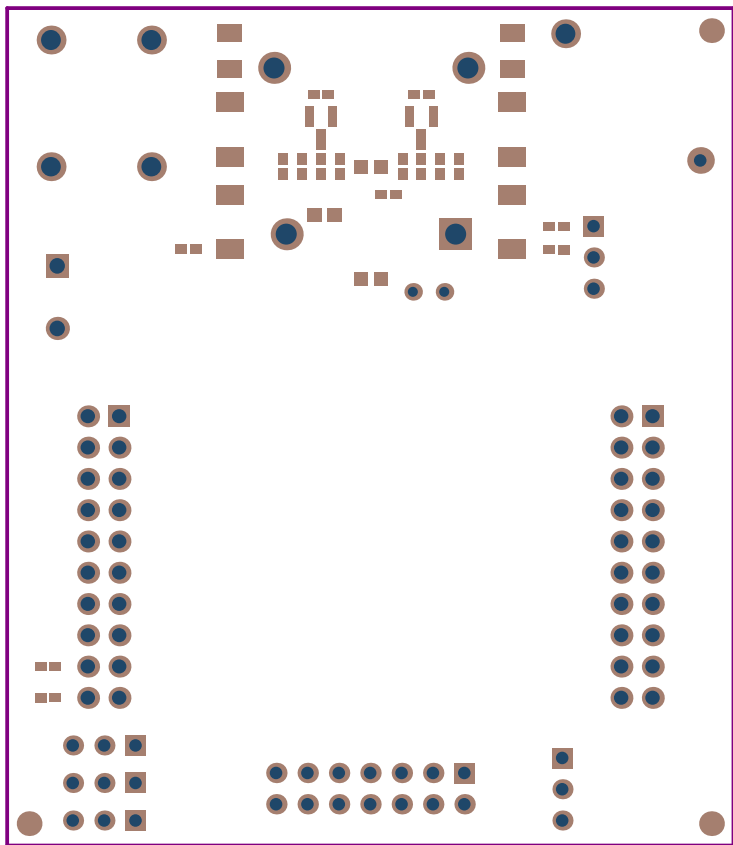
PLOT NAME = MidLayer2

GENERATED : 10/1/2014 11:55:07 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00168	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/1/2014 11:55:07 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00168

REV: E1

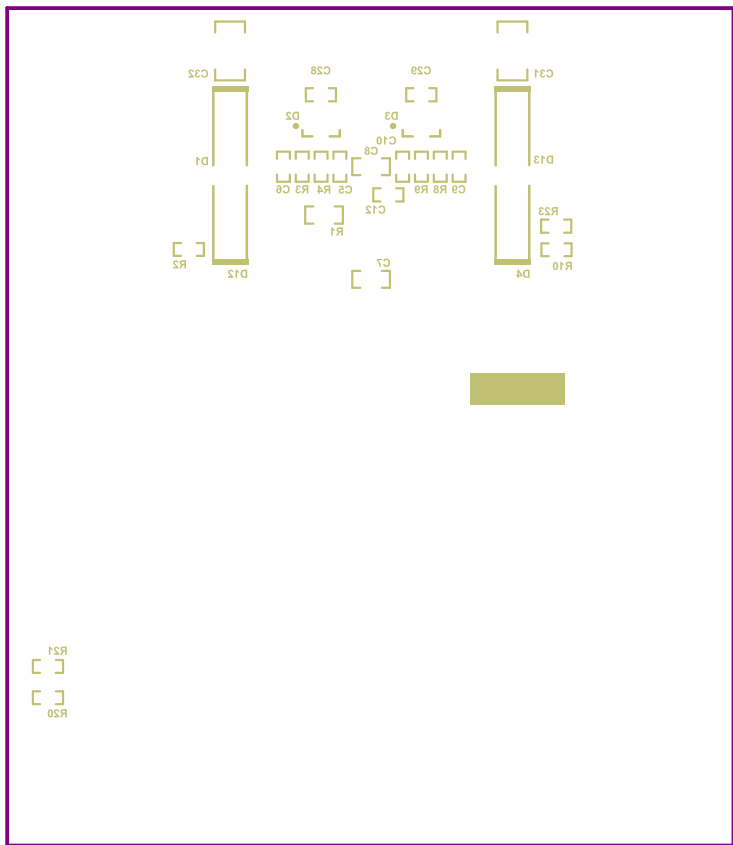
SVN REV: Not In VersionControl

LAYER NAME = Bottom Solder

PLOT NAME = Bottom Solder Mask

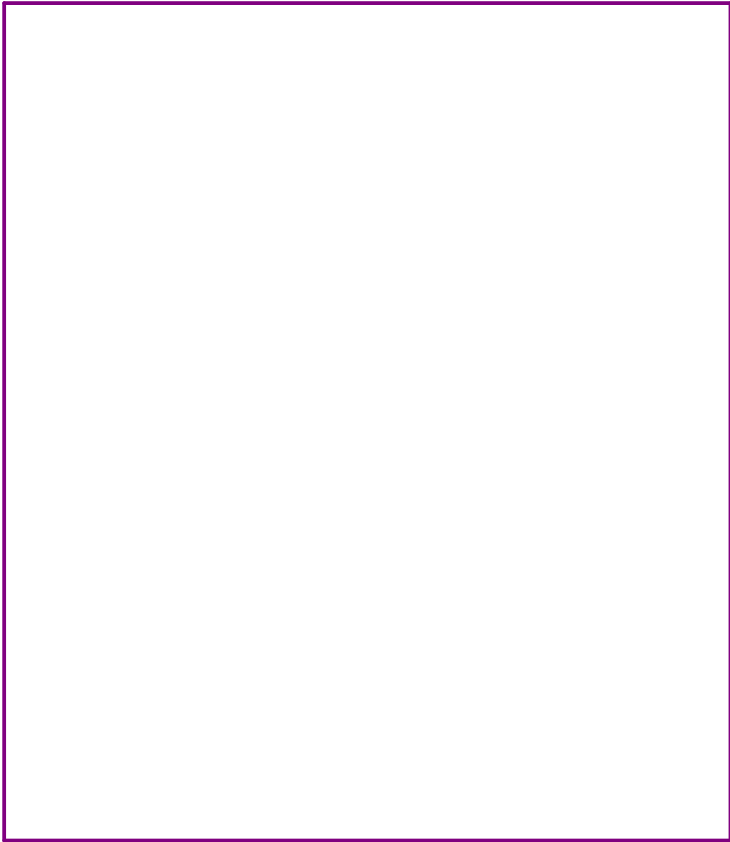
GENERATED : 10/1/2014 11:55:07 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00168	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/1/2014	11:55:07 AM	TEXAS INSTRUMENTS





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00168	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Board Outline	GENERATED : 10/1/2014 11:55:07 AM	TEXAS INSTRUMENTS	

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